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(54) **SEMICONDUCTOR APPARATUS**

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(57)**ABSTRACT**

A semiconductor apparatus includes: a semiconductor module; a cooler including flow paths through which a refrigerant flows; a casing including a bottom surface; at least one first fixing member fixing the cooler to the bottom surface; and at least one second fixing member fixing the cooler to the bottom surface. The cooler includes: an outer surface directed to the bottom surface of the casing; an inner surface that is a part of wall surfaces of the flow paths on an opposite side to the outer surface; an outer wall to which the at least one first fixing member is connected; and an outer wall that is on an opposite side to the outer wall and to which the at least one second fixing member is connected. The semiconductor module is positioned between the bottom surface of the casing and the outer surface of the cooler, and is pressed by these two surfaces.

